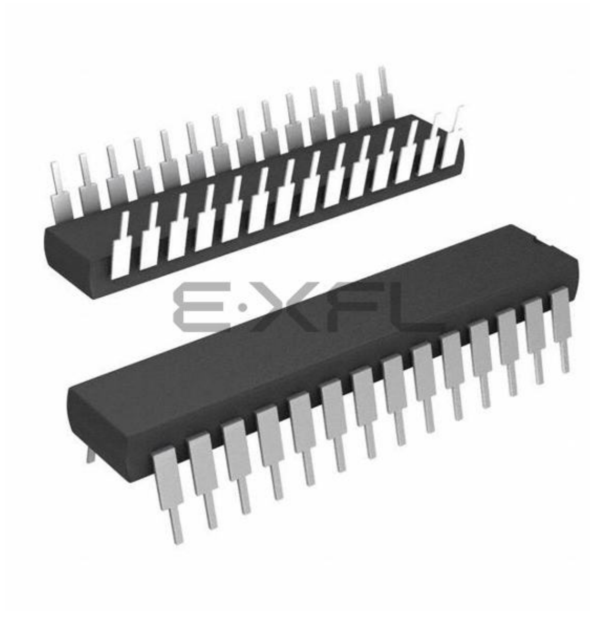

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f722-i-sp

PIC16(L)F72X Family Types

Device	Data Sheet Index	Program Memory Flash (words)	Data SRAM (bytes)	High-Endurance Flash Memory (bytes)	I/O's(2)	8-bit ADC (ch)	CapSense (ch)	Timers (8/16-bit)	AUSART	SSP (I^2C/SPI)	CCP	Debug(1)	XLP
PIC16(L)F707	(1)	8192	363	0	36	14	32	4/2	1	1	2	I	Y
PIC16(L)F720	(2)	2048	128	128	18	12	—	2/1	1	1	1	I	Y
PIC16(L)F721	(2)	4096	256	128	18	12	—	2/1	1	1	1	I	Y
PIC16(L)F722	(4)	2048	128	0	25	11	8	2/1	1	1	2	I	Y
PIC16(L)F722A	(3)	2048	128	0	25	11	8	2/1	1	1	2	I	Y
PIC16(L)F723	(4)	4096	192	0	25	11	8	2/1	1	1	2	I	Y
PIC16(L)F723A	(3)	4096	192	0	25	11	8	2/1	1	1	2	I	Y
PIC16(L)F724	(4)	4096	192	0	36	14	16	2/1	1	1	2	I	Y
PIC16(L)F726	(4)	8192	368	0	25	11	8	2/1	1	1	2	I	Y
PIC16(L)F727	(4)	8192	368	0	36	14	16	2/1	1	1	2	I	Y

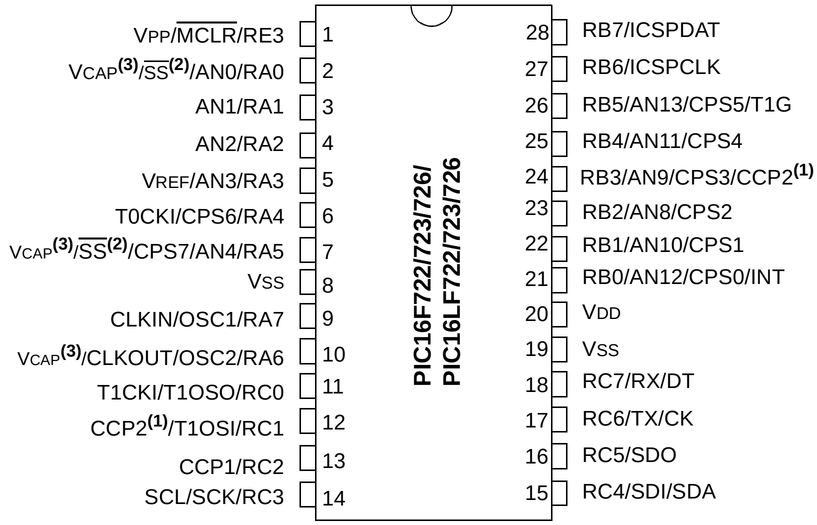
Note 1: I - Debugging, Integrated on Chip; H - Debugging, Requires Debug Header.
2: One pin is input-only.

Data Sheet Index: (Unshaded devices are described in this document.)

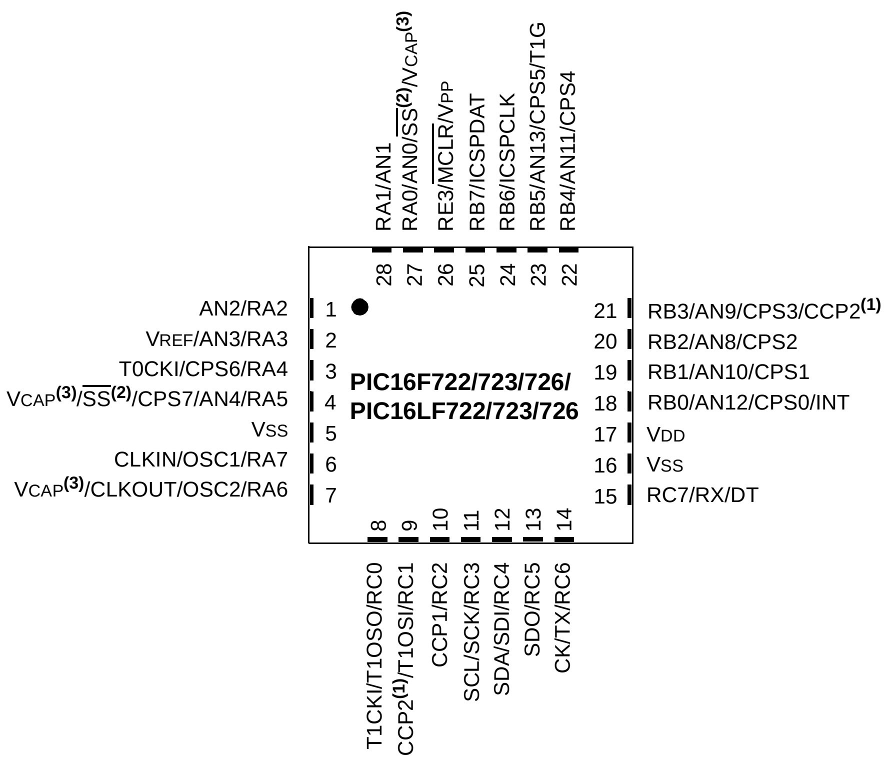
1: DS41418 PIC16(L)F707 Data Sheet, 40/44-Pin Flash, 8-bit Microcontrollers
2: DS41430 PIC16(L)F720/721 Data Sheet, 20-Pin Flash, 8-bit Microcontrollers
3: DS41417 PIC16(L)F722A/723A Data Sheet, 28-Pin Flash, 8-bit Microcontrollers
4: DS41341 PIC16(L)F72X Data Sheet, 28/40/44-Pin Flash, 8-bit Microcontrollers

Pin Diagrams – 28-PIN PDIP/SOIC/SSOP/QFN/UQFN (PIC16F722/723/726/PIC16LF722/723/726)

PDIP, SOIC, SSOP

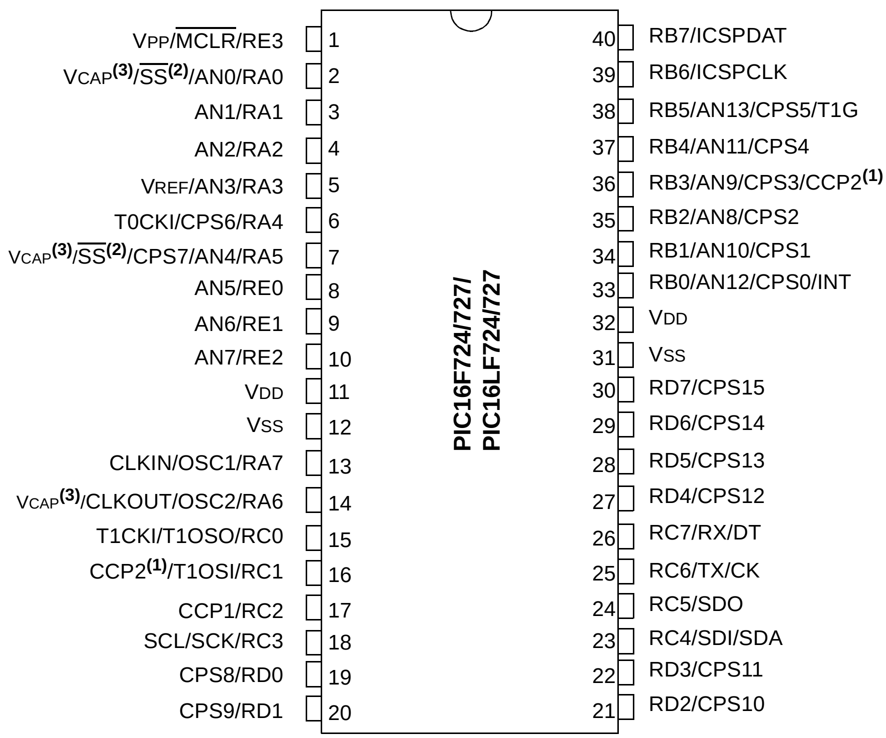


QFN, UQFN



Note 1: CCP2 pin location may be selected as RB3 or RC1.
2: SS pin location may be selected as RA5 or RA0.
3: PIC16F722/723/726 devices only.

Pin Diagrams – 40-PIN PDIP (PIC16F724/727/PIC16LF724/727)



Note 1: CCP2 pin location may be selected as RB3 or RC1.
2: SS pin location may be selected as RA5 or RA0.
3: PIC16F724/727 devices only.

EXAMPLE 4-1: SAVING W, STATUS AND PCLATH REGISTERS IN RAM

```
MOVWF   W_TEMP          ;Copy W to W_TEMP register
SWAPF   STATUS,W        ;Swap status to be saved into W
                        ;Swaps are used because they do not affect the status bits
BANKSEL STATUS_TEMP     ;Select regardless of current bank
MOVWF   STATUS_TEMP     ;Copy status to bank zero STATUS_TEMP register
MOVF    PCLATH,W        ;Copy PCLATH to W register
MOVWF   PCLATH_TEMP     ;Copy W register to PCLATH_TEMP
:
:(ISR)                  ;Insert user code here
:
BANKSEL STATUS_TEMP     ;Select regardless of current bank
MOVF    PCLATH_TEMP,W   ;
MOVWF   PCLATH          ;Restore PCLATH
SWAPF   STATUS_TEMP,W   ;Swap STATUS_TEMP register into W
                        ;(sets bank to original state)
MOVWF   STATUS          ;Move W into STATUS register
SWAPF   W_TEMP,F        ;Swap W_TEMP
SWAPF   W_TEMP,W        ;Swap W_TEMP into W
```

4.5.1 INTCON REGISTER

The INTCON register is a readable and writable register, which contains the various enable and flag bits for TMR0 register overflow, PORTB change and external RB0/INT/SEG0 pin interrupts.

Note:	Interrupt flag bits are set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE of the INTCON register. User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

TABLE 6-1: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	0000 0000	0000 0000
ADCON1	—	ADCS2	ADCS1	ADCS0	—	—	ADREF1	ADREF0	-000 --00	-000 --00
ANSELA	—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	--11 1111	--11 1111
APFCON	—	—	—	—	—	—	SSSEL	CCP2SEL	---- --00	---- --00
CPSCON0	CPSON	—	—	—	CPSRNG1	CPSRNG0	CPSOUT	T0XCS	0--- 0000	0--- 0000
CPSCON1	—	—	—	—	CPSCH3	CPSCH2	CPSCH1	CPSCH0	---- 0000	---- 0000
CONFIG2(1)	—	—	VCAPEN1	VCAPEN0	—	—	—	—	—	—
OPTION_REG	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
PORTA	RA7	RA6	RA5	RA4	RA3	RA2	RA1	RA0	xxxx xxxx	xxxx xxxx
SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1111 1111	1111 1111

Legend: x = unknown, u = unchanged, – = unimplemented locations read as ‘0’. Shaded cells are not used by PORTA.

Note 1: PIC16F72X only.

REGISTER 6-7: WPUB: WEAK PULL-UP PORTB REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-0 **WPUB<7:0>**: Weak Pull-up Register bits
`1` = Pull-up enabled
`0` = Pull-up disabled

Note 1: Global $\overline{\text{RBPU}}$ bit of the OPTION register must be cleared for individual pull-ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is in configured as an output.

REGISTER 6-8: IOCB: INTERRUPT-ON-CHANGE PORTB REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
IOCB7	IOCB6	IOCB5	IOCB4	IOCB3	IOCB2	IOCB1	IOCB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-0 **IOCB<7:0>:** Interrupt-on-Change PORTB Control bits
`1` = Interrupt-on-change enabled
`0` = Interrupt-on-change disabled

REGISTER 6-9: ANSELB: PORTB ANALOG SELECT REGISTER

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as ‘`0`’
bit 5-0 **ANSB<5:0>**: Analog Select between Analog or Digital Function on Pins RB<5:0>, respectively
`0` = Digital I/O. Pin is assigned to port or Digital special function.
`1` = Analog input. Pin is assigned as analog input[(1)]. Digital Input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

7.2 Clock Source Modes

Clock source modes can be classified as external or internal.

- Internal clock source (INTOSC) is contained within the oscillator module and derived from a 500 kHz high precision oscillator. The oscillator module has eight selectable output frequencies, with a maximum internal frequency of 16 MHz.
- External clock modes rely on external circuitry for the clock source. Examples are: oscillator modules (EC mode), quartz crystal resonators or ceramic resonators (LP, XT and HS modes) and Resistor-Capacitor (RC) mode circuits.

The system clock can be selected between external or internal clock sources via the FOSC bits of the Configuration Word 1.

7.3 Internal Clock Modes

The oscillator module has eight output frequencies derived from a 500 kHz high precision oscillator. The IRCF bits of the OSCCON register select the postscaler applied to the clock source dividing the frequency by 1, 2, 4 or 8. Setting the PLLEN bit of the Configuration Word 1 locks the internal clock source to 16 MHz before the postscaler is selected by the IRCF bits. The PLLEN bit must be set or cleared at the time of programming; therefore, only the upper or low four clock source frequencies are selectable in software.

7.3.1 INTOSC AND INTOSCIO MODES

The INTOSC and INTOSCIO modes configure the internal oscillators as the system clock source when the device is programmed using the oscillator selection or the FOSC<2:0> bits in the CONFIG1 register. See **Section 8.0 “Device Configuration”** for more information.

In INTOSC mode, OSC1/CLKIN is available for general purpose I/O. OSC2/CLKOUT outputs the selected internal oscillator frequency divided by 4. The CLKOUT signal may be used to provide a clock for external circuitry, synchronization, calibration, test or other application requirements.

In INTOSCIO mode, OSC1/CLKIN and OSC2/CLKOUT are available for general purpose I/O.

7.3.2 FREQUENCY SELECT BITS (IRCF)

The output of the 500 kHz INTOSC and 16 MHz INTOSC, with Phase-Locked Loop enabled, connect to a postscaler and multiplexer (see Figure 7-1). The Internal Oscillator Frequency Select bits (IRCF) of the OSCCON register select the frequency output of the internal oscillator. Depending upon the PLLEN bit, one of four frequencies of two frequency sets can be selected via software:

If PLLEN = `1`, frequency selection is as follows:

- 16 MHz
- 8 MHz (default after Reset)
- 4 MHz
- 2 MHz

If PLLEN = `0`, frequency selection is as follows:

- 500 kHz
- 250 kHz (default after Reset)
- 125 kHz
- 62.5 kHz

Note:	Following any Reset, the IRCF<1:0> bits of the OSCCON register are set to ‘`10`’ and the frequency selection is set to 8 MHz or 250 kHz. The user can modify the IRCF bits to select a different frequency.

There is no start-up delay before a new frequency selected in the IRCF bits takes effect. This is because the old and new frequencies are derived from INTOSC via the postscaler and multiplexer.

Start-up delay specifications are located in the Table 23-2 in **Section 23.0 “Electrical Specifications”**.

9.1.5 INTERRUPTS

The ADC module allows for the ability to generate an interrupt upon completion of an Analog-to-Digital conversion. The ADC interrupt flag is the ADIF bit in the PIR1 register. The ADC interrupt enable is the ADIE bit in the PIE1 register. The ADIF bit must be cleared in software.

Note 1:	The ADIF bit is set at the completion of every conversion, regardless of whether or not the ADC interrupt is enabled.
2:	The ADC operates during Sleep only when the FRC oscillator is selected.

This interrupt can be generated while the device is operating or while in Sleep. If the device is in Sleep, the interrupt will wake-up the device. Upon waking from Sleep, the next instruction following the SLEEP instruction is always executed. If the user is attempting to wake-up from Sleep and resume in-line code execution, the GIE and PEIE bits of the INTCON register must be disabled. If the GIE and PEIE bits of the INTCON register are enabled, execution will switch to the Interrupt Service Routine.

Please refer to **Section 9.1.5 "Interrupts"** for more information.

9.2 ADC Operation

9.2.1 STARTING A CONVERSION

To enable the ADC module, the ADON bit of the ADCON0 register must be set to a '1'. Setting the GO/$\overline{\text{DONE}}$ bit of the ADCON0 register to a '1' will start the Analog-to-Digital conversion.

Note:	The GO/$\overline{\text{DONE}}$ bit should not be set in the same instruction that turns on the ADC. Refer to **Section 9.2.6 "A/D Conversion Procedure"**.

9.2.2 COMPLETION OF A CONVERSION

When the conversion is complete, the ADC module will:

- Clear the GO/$\overline{\text{DONE}}$ bit
- Set the ADIF Interrupt Flag bit
- Update the ADRES register with new conversion result

9.2.3 TERMINATING A CONVERSION

If a conversion must be terminated before completion, the GO/$\overline{\text{DONE}}$ bit can be cleared in software. The ADRES register will be updated with the partially complete Analog-to-Digital conversion sample. Incomplete bits will match the last bit converted.

Note:	A device Reset forces all registers to their Reset state. Thus, the ADC module is turned off and any pending conversion is terminated.

9.2.4 ADC OPERATION DURING SLEEP

The ADC module can operate during Sleep. This requires the ADC clock source to be set to the FRC option. When the FRC clock source is selected, the ADC waits one additional instruction before starting the conversion. This allows the SLEEP instruction to be executed, which can reduce system noise during the conversion. If the ADC interrupt is enabled, the device will wake-up from Sleep when the conversion completes. If the ADC interrupt is disabled, the ADC module is turned off after the conversion completes, although the ADON bit remains set.

When the ADC clock source is something other than FRC, a SLEEP instruction causes the present conversion to be aborted and the ADC module is turned off, although the ADON bit remains set.

9.2.5 SPECIAL EVENT TRIGGER

The Special Event Trigger of the CCP module allows periodic ADC measurements without software intervention. When this trigger occurs, the GO/$\overline{\text{DONE}}$ bit is set by hardware and the Timer1 counter resets to zero.

Using the Special Event Trigger does not assure proper ADC timing. It is the user's responsibility to ensure that the ADC timing requirements are met.

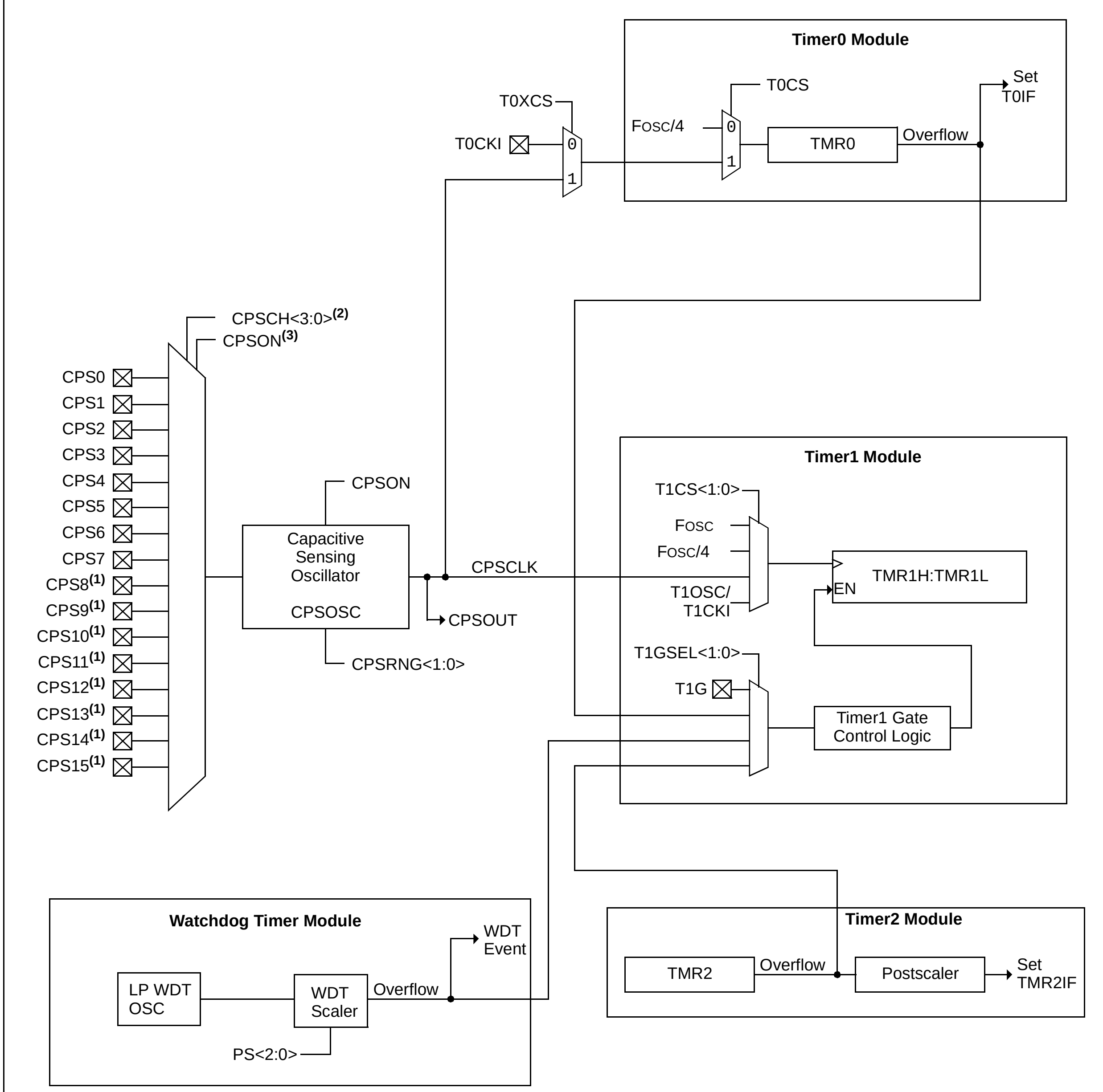
Refer to **Section 15.0 "Capture/Compare/PWM (CCP) Module"** for more information.

14.0 CAPACITIVE SENSING MODULE

The capacitive sensing module allows for an interaction with an end user without a mechanical interface. In a typical application, the capacitive sensing module is attached to a pad on a printed circuit board (PCB), which is electrically isolated from the end user. When the end user places their finger over the PCB pad, a capacitive load is added, causing a frequency shift in the capacitive sensing module. The capacitive sensing module requires software and at least one timer resource to determine the change in frequency. Key features of this module include:

- Analog MUX for monitoring multiple inputs
- Capacitive sensing oscillator
- Multiple timer resources
- Software control
- Operation during Sleep

FIGURE 14-1: CAPACITIVE SENSING BLOCK DIAGRAM



Note 1: Channels CPS<15:8> are implemented on PIC16F724/727/PIC16LF724/727 only.
2: CPSCH3 is not implemented on PIC16F722/723/726/PIC16LF722/723/726.
3: If CPSON = 0, disabling capacitive sensing, no channel is selected.

TABLE 15-4: SUMMARY OF REGISTERS ASSOCIATED WITH COMPARE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ADCON0	—	—	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON	--00 0000	--00 0000
ANSELB	—	—	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	ANSB0	--11 1111	--11 1111
APFCON	—	—	—	—	—	—	SSSEL	CCP2SEL	---- --00	---- --00
CCP1CON	—	—	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
CCP2CON	—	—	DC2B1	DC2B0	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000
CCPRxL	Capture/Compare/PWM Register X Low Byte								xxxx xxxx	uuuu uuuu
CCPRxH	Capture/Compare/PWM Register X High Byte								xxxx xxxx	uuuu uuuu
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIE2	—	—	—	—	—	—	—	CCP2IE	---- ---0	---- ---0
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PIR2	—	—	—	—	—	—	—	CCP2IF	---- ---0	---- ---0
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	0000 00-0	uuuu uu-u
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/$\overline{\text{DONE}}$	T1GVAL	T1GSS1	T1GSS0	0000 0x00	0000 0x00
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	uuuu uuuu
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111

Legend: - = Unimplemented locations, read as '0', u = unchanged, x = unknown. Shaded cells are not used by the Compare.

16.3.1.4 Synchronous Master Reception

Data is received at the RX/DT pin. The RX/DT pin output driver is automatically disabled when the AUSART is configured for synchronous master receive operation.

In Synchronous mode, reception is enabled by setting either the Single Receive Enable bit (SREN of the RCSTA register) or the Continuous Receive Enable bit (CREN of the RCSTA register).

When SREN is set and CREN is clear, only as many clock cycles are generated as there are data bits in a single character. The SREN bit is automatically cleared at the completion of one character. When CREN is set, clocks are continuously generated until CREN is cleared. If CREN is cleared in the middle of a character the CK clock stops immediately and the partial character is discarded. If SREN and CREN are both set, then SREN is cleared at the completion of the first character and CREN takes precedence.

To initiate reception, set either SREN or CREN. Data is sampled at the RX/DT pin on the trailing edge of the TX/CK clock pin and is shifted into the Receive Shift Register (RSR). When a complete character is received into the RSR, the RCIF bit of the PIR1 register is set and the character is automatically transferred to the two character receive FIFO. The Least Significant eight bits of the top character in the receive FIFO are available in RCREG. The RCIF bit remains set as long as there are unread characters in the receive FIFO.

16.3.1.5 Slave Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a slave receives the clock on the TX/CK line. The TX/CK pin output driver is automatically disabled when the device is configured for synchronous slave transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One data bit is transferred for each clock cycle. Only as many clock cycles should be received as there are data bits.

16.3.1.6 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before RCREG is read to access the FIFO. When this happens the OERR bit of the RCSTA register is set. Previous data in the FIFO will not be overwritten. The two characters in the FIFO buffer can be read, however, no additional characters will be received until the error is cleared. The OERR bit can only be cleared by clearing the overrun condition. If the overrun error occurred when the SREN bit is set and CREN is clear then the error is cleared by reading RCREG. If the overrun occurred when the CREN bit is set then the error condition is cleared by either clearing the CREN bit of the RCSTA register.

16.3.1.7 Receiving 9-bit Characters

The AUSART supports 9-bit character reception. When the RX9 bit of the RCSTA register is set, the AUSART will shift 9-bits into the RSR for each character received. The RX9D bit of the RCSTA register is the ninth, and Most Significant, data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RCREG.

Address detection in Synchronous modes is not supported, therefore, the ADDEN bit of the RCSTA register must be cleared.

16.3.1.8 Synchronous Master Reception Setup:

1. Initialize the SPBRG register for the appropriate baud rate. Set or clear the BRGH bit, as required, to achieve the desired baud rate.
2. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
3. Ensure bits CREN and SREN are clear.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit reception is desired, set bit RX9.
6. Verify address detection is disabled by clearing the ADDEN bit of the RCSTA register.
7. Start reception by setting the SREN bit or for continuous reception, set the CREN bit.
8. Interrupt flag bit RCIF of the PIR1 register will be set when reception of a character is complete. An interrupt will be generated if the RCIE interrupt enable bit of the PIE1 register was set.
9. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
10. Read the 8-bit received data by reading the RCREG register.
11. If an overrun error occurs, clear the error by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit, which resets the AUSART.

TABLE 17-1: SUMMARY OF REGISTERS ASSOCIATED WITH SPI OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
ANSELA	—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	--11 1111	--11 1111
APFCON	—	—	—	—	—	—	SSSEL	CCP2SEL	---- --00	---- --00
INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
PR2	Timer2 Period Register								1111 1111	1111 1111
SSPBUF	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	uuuu uuuu
SSPCON	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
SSPSTAT	SMP	CKE	D/$\overline{\text{A}}$	P	S	R/$\overline{\text{W}}$	UA	BF	0000 0000	0000 0000
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1111 1111	1111 1111
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	1111 1111	1111 1111
T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000

Legend: x = unknown, u = unchanged, – = unimplemented, read as '0'. Shaded cells are not used by the SSP in SPI mode.

19.0 POWER-DOWN MODE (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If the Watchdog Timer is enabled:

- WDT will be cleared but keeps running.
- $\overline{PD}$ bit of the STATUS register is cleared.
- $\overline{TO}$ bit of the STATUS register is set.
- Oscillator driver is turned off.
- Timer1 oscillator is unaffected
- I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).

For lowest current consumption in this mode, all I/O pins should be either at V_{DD} or V_{SS}, with no external circuitry drawing current from the I/O pin. I/O pins that are high-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull-ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level when external $\overline{MCLR}$ is enabled.

Note:	A Reset generated by a WDT time out does not drive $\overline{MCLR}$ pin low.

19.1 Wake-up from Sleep

The device can wake up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin.
2. Watchdog Timer wake-up (if WDT was enabled).
3. Interrupt from RB0/INT pin, PORTB change or a peripheral interrupt.

The first event will cause a device Reset. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device Reset. The $\overline{PD}$ bit, which is set on power-up, is cleared when Sleep is invoked. $\overline{TO}$ bit is cleared if WDT wake-up occurred.

The following peripheral interrupts can wake the device from Sleep:

1. TMR1 Interrupt. Timer1 must be operating as an asynchronous counter.
2. USART Receive Interrupt (Synchronous Slave mode only)
3. A/D conversion (when A/D clock source is RC)
4. Interrupt-on-change
5. External Interrupt from INT pin
6. Capture event on CCP1 or CCP2
7. SSP Interrupt in SPI or I^2C Slave mode

Other peripherals cannot generate interrupts since during Sleep, no on-chip clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction, then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

Note:	If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from Sleep. The SLEEP instruction is completely executed.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

TABLE 23-2: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**	**Freq. Tolerance**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS08	HFOSC	Internal Calibrated HFINTOSC Frequency(2)	±2%	—	16.0	—	MHz	0°C ≤ TA ≤ +85°C, VDD ≥ 2.5V
			±5%	—	16.0	—	MHz	-40°C ≤ TA ≤ +125°C
OS08A	MFOSC	Internal Calibrated MFINTOSC Frequency(2)	±2%	—	500	—	kHz	0°C ≤ TA ≤ +85°C VDD ≥ 2.5V
			±5%	—	500	10	kHz	-40°C ≤ TA ≤ +125°C
OS10*	TIOSC ST	HFINTOSC Wake-up from Sleep Start-up Time	—	—	5	8	μs	
		MFINTOSC Wake-up from Sleep Start-up Time	—	—	20	30	μs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μF and 0.01 μF values in parallel are recommended.

3: By design.

FIGURE 23-7: CLKOUT AND I/O TIMING

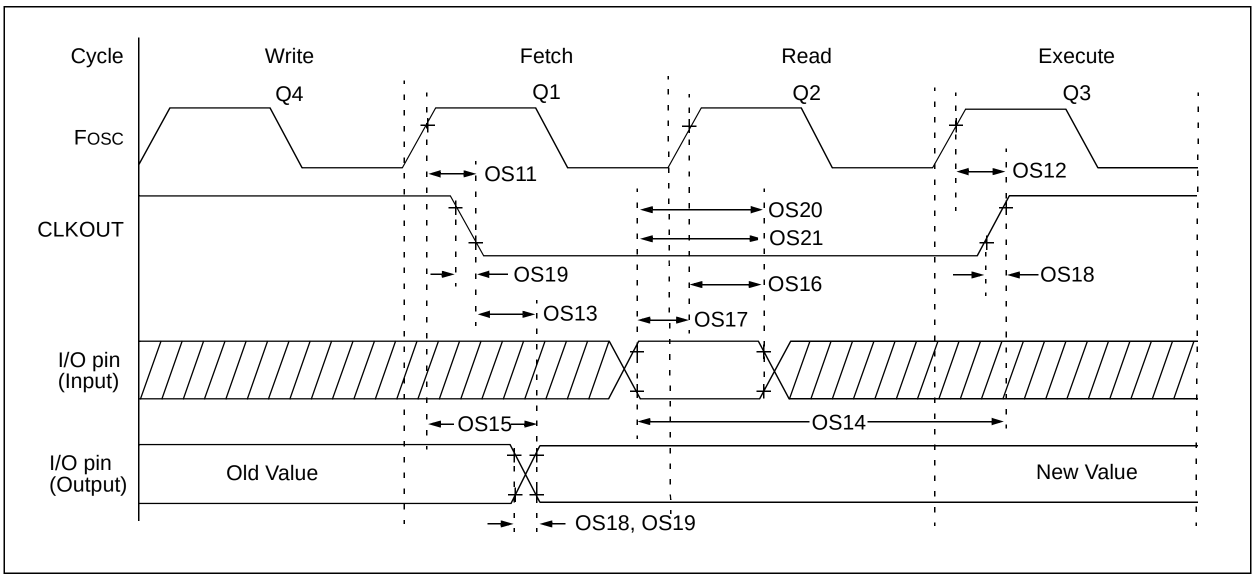


TABLE 23-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER, AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated)
Operating Temperature -40°C ≤ TA ≤ +125°C

Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
30	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2 5	— —	— —	μs μs	VDD = 3.3-5V, -40°C to +85°C VDD = 3.3-5V
31	TWDTLP	Low Power Watchdog Timer Time-out Period (No Prescaler)	10	18	27	ms	VDD = 3.3V-5V
32	TOST	Oscillator Start-up Timer Period(1), (2)	—	1024	—	Tosc	**(Note 3)**
33*	TPWRT	Power-up Timer Period, $\overline{\text{PWRTE}}$ = 0	40	65	140	ms	
34*	TIOZ	I/O high-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	2.0	μs	
35	VBOR	Brown-out Reset Voltage	2.38 1.80	2.5 1.9	2.73 2.11	V	BORV=2.5V BORV=1.9V
36*	VHYST	Brown-out Reset Hysteresis	0	25	50	mV	-40°C to +85°C
37*	TBORDC	Brown-out Reset DC Response Time	1	3	5 10	μs	VDD ≤ VBOR, -40°C to +85°C VDD ≤ VBOR

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: By design.

3: Period of the slower clock.

4: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μF and 0.01 μF values in parallel are recommended.

FIGURE 23-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

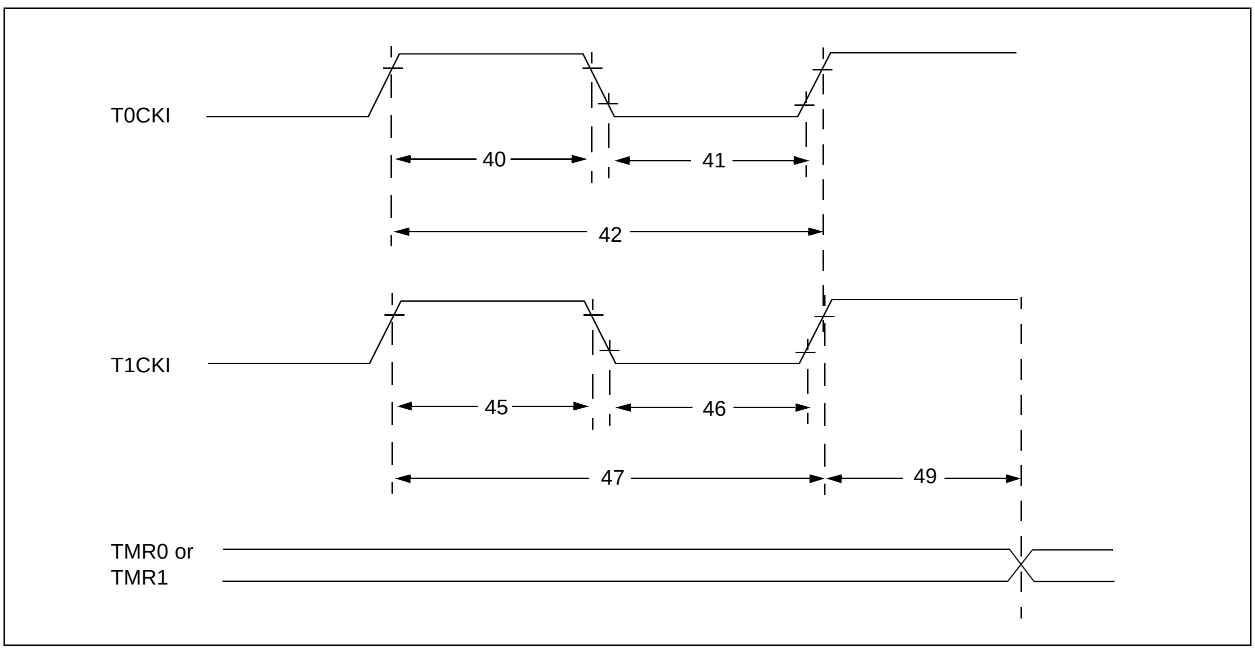
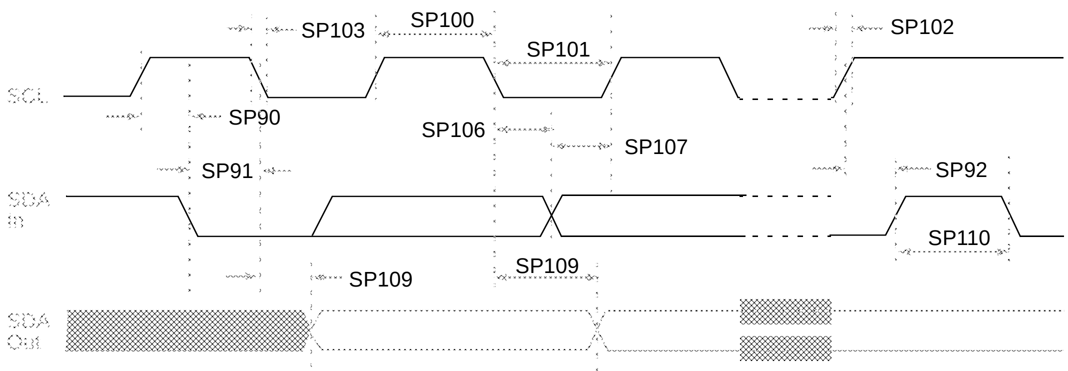


TABLE 23-12: I²C BUS START/STOP BITS REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ	Max.	Units	Conditions
SP90*	TSU:STA	Start condition Setup time	100 kHz mode	4700	—	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	—		
SP91*	THD:STA	Start condition Hold time	100 kHz mode	4000	—	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	—		
SP92*	TSU:STO	Stop condition Setup time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
SP93	THD:STO	Stop condition Hold time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

FIGURE 23-21: I²C BUS DATA TIMING



Note: Refer to Figure 23-2 for load conditions.

FIGURE 24-15: PIC16F722/3/4/6/7 TYPICAL IDD vs. VDD OVER FOSC, XT MODE, VCAP = 0.1 µF

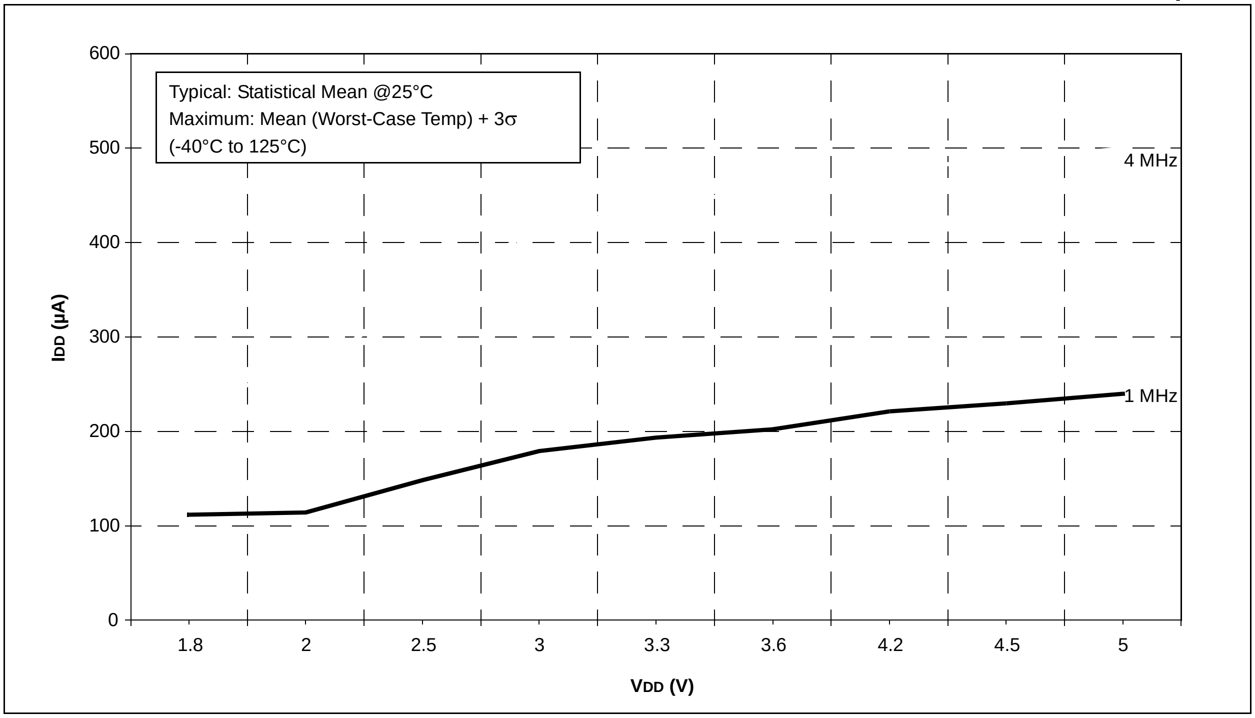


FIGURE 24-16: PIC16LF722/3/4/6/7 TYPICAL IDD vs. VDD OVER FOSC, XT MODE

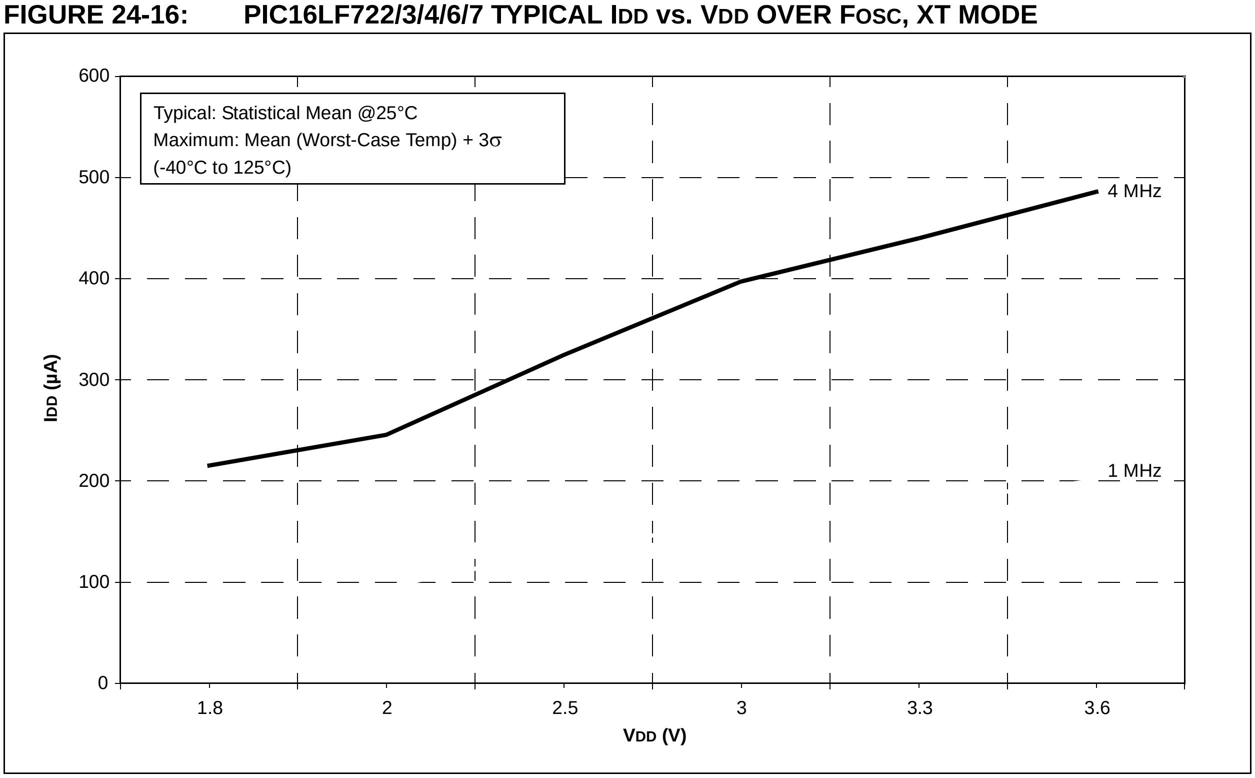


FIGURE 24-23: PIC16F722/3/4/6/7 TYPICAL IDD vs. FOSC OVER VDD, INTOSC MODE, VCAP =0.1µF

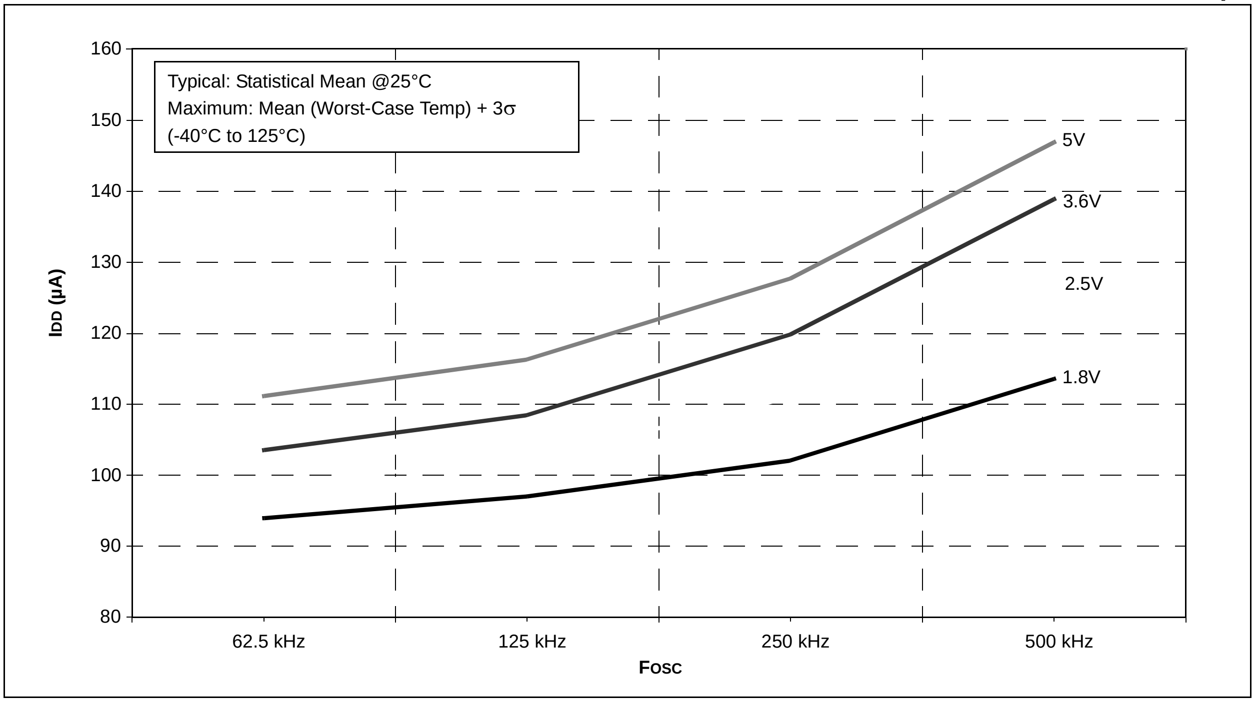


FIGURE 24-24: PIC16LF722/3/4/6/7 TYPICAL IDD vs. FOSC OVER VDD, INTOSC MODE

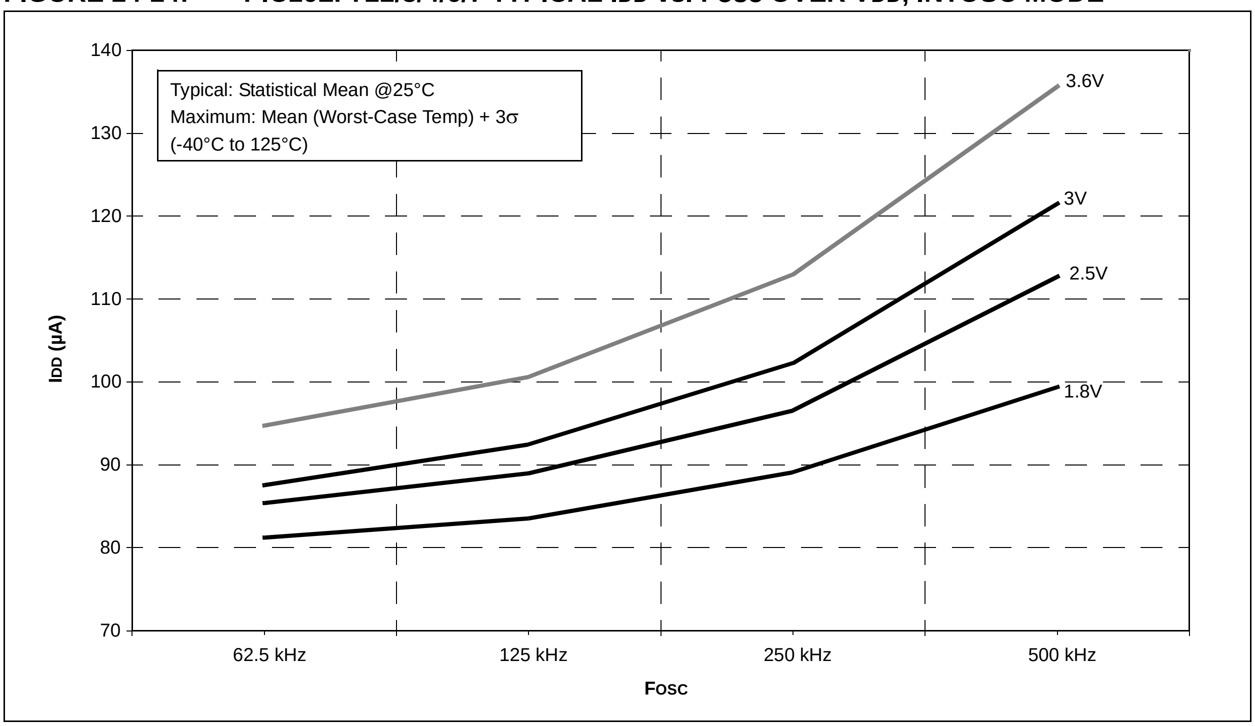


FIGURE 24-47: PIC16F722/3/4/6/7 WDT IPD vs. VDD, VCAP = 0.1 µF

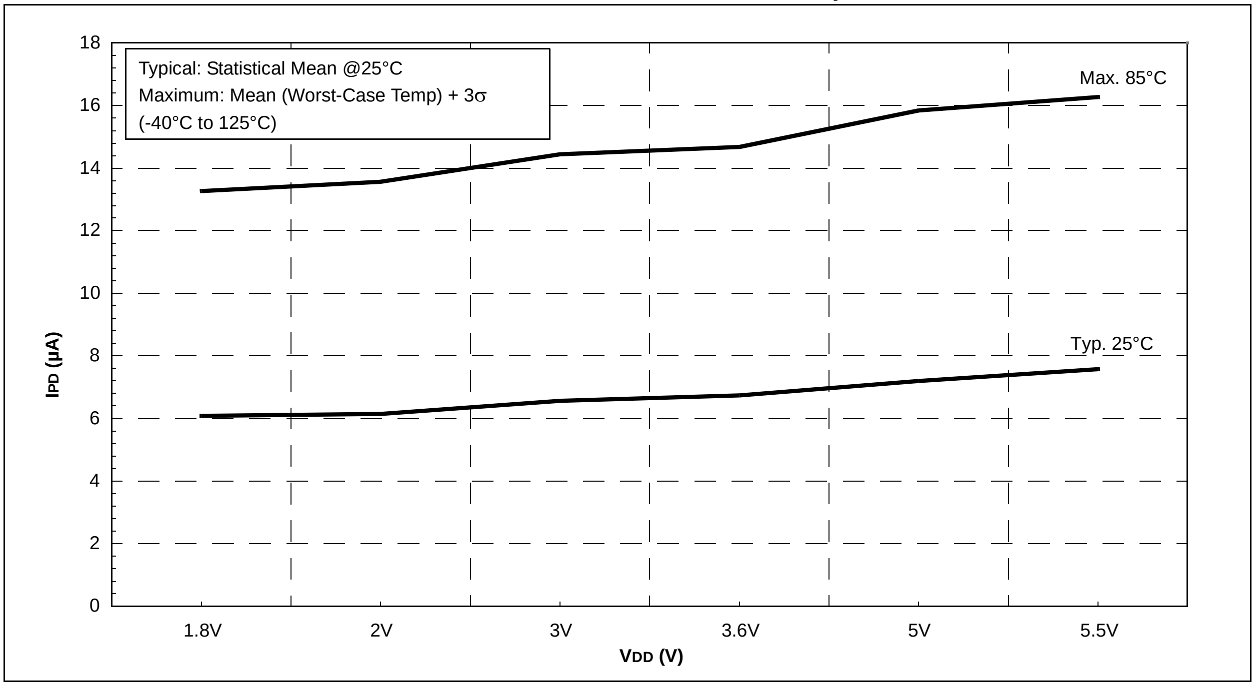
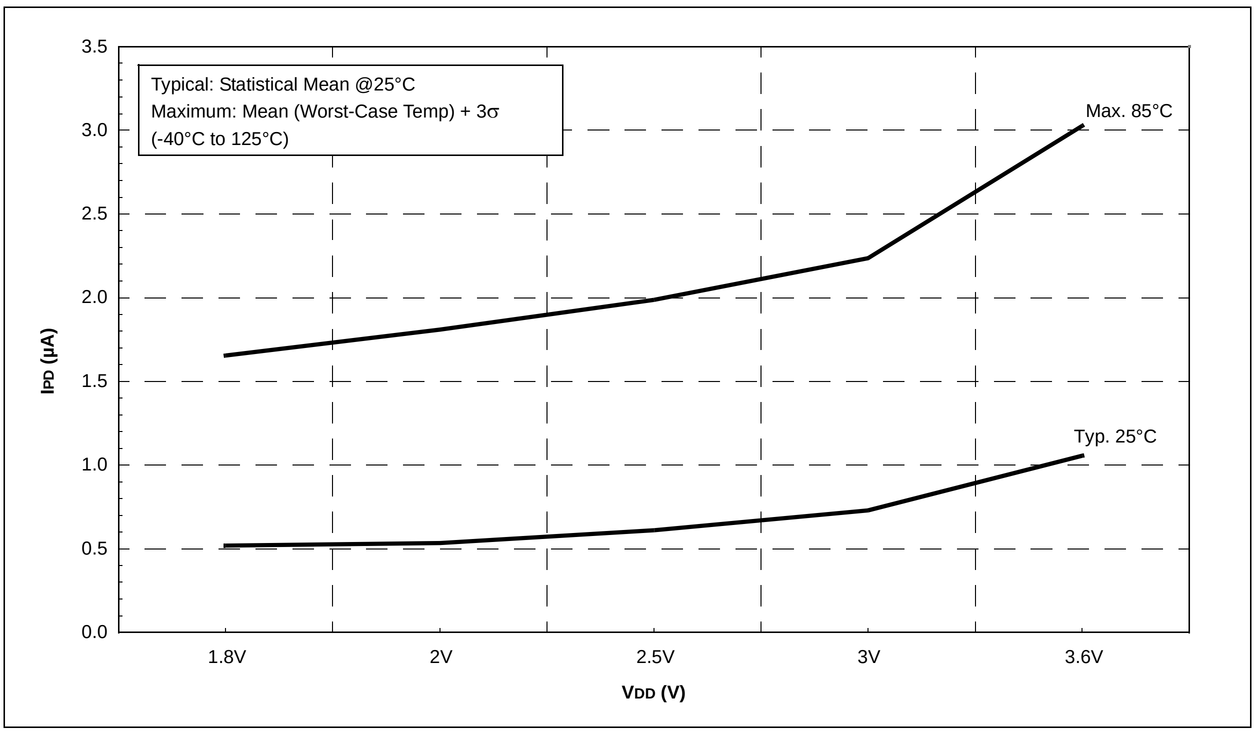
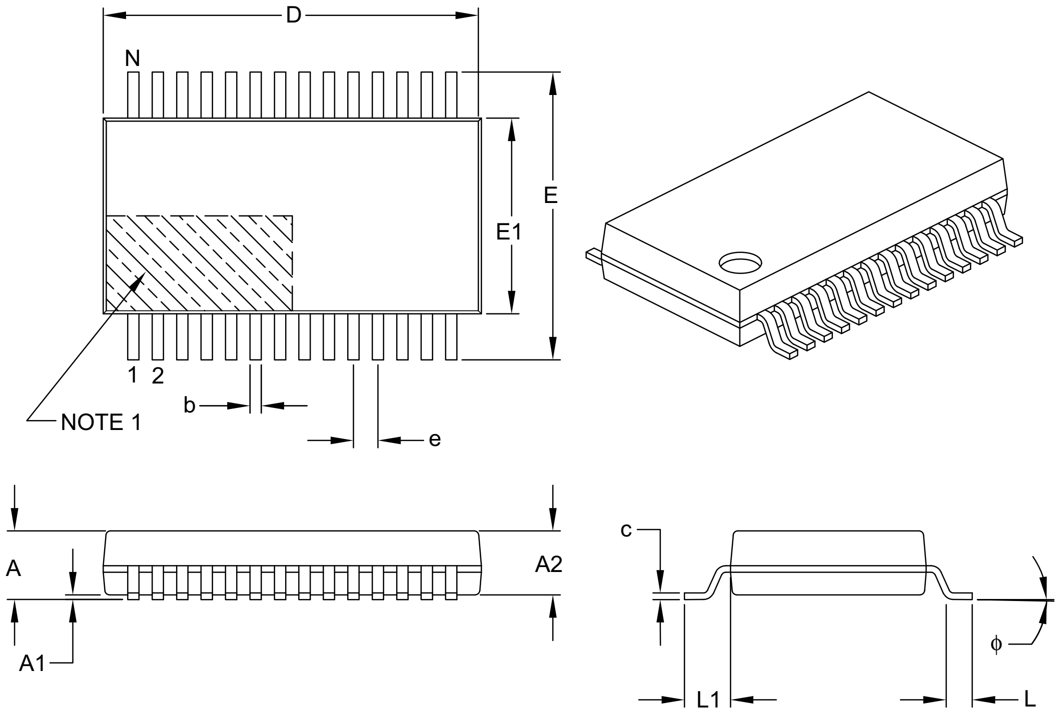


FIGURE 24-48: PIC16LF722/3/4/6/7 WDT IPD vs. VDD



28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B